

(12) United States Design Patent (10) Patent No.: US D471,168 S Ge et al. Mar. 4, 2003 (45) **Date of Patent:** **

HEAT DISSIPATING RF ELECTRONICS (54)HOUSING

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(**) Term: 14 Years

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CLAIM (57)

The ornamental design for a heat dissipating RF electronics housing, as shown and described.

DESCRIPTION

FIG. 1 is a perspective photographic view from a first side of the electronics housing according to the invention. FIG. 2 is a perspective photographic view from the opposite side of the housing according to FIG. 1. FIG. 3 is a top photographic view of the housing according to FIG. 1. FIG. 4 is a side photographic view of the housing according to FIG. 1.

FIG. 5 is a perspective photographic view from an end of the housing according to FIG. 1.

FIG. 6 is an end view of the housing according to FIG. 5; and,

FIG. 7 is a photographic view of the bottom of the housing according to FIG. 1.

1 Claim, 3 Drawing Sheets



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